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Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







LXA20T600 Qspeed[™] Family

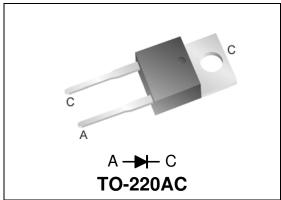


600 V, 20 A X-Series PFC Diode

Product Summary

I _{F(AVG)}	20	Α
V_{RRM}	600	V
Q _{RR} (Typ at 125 °C)	140	nC
I _{RRM} (Typ at 125 °C)	5.0	Α
Softness t _b /t _a (Typ at 125 °C)	0.4	

Pin Assignment



RoHS Compliant

Package uses Lead-free plating and Green mold compound. Halogen free per IEC 61249-2-21.

General Description

This device has the lowest Q_{RR} of any 600V Silicon diode. Its recovery characteristics increase efficiency, reduce EMI and eliminate snubbers.

Applications

- Power Factor Correction (PFC) Boost Diode
- Motor drive circuits
- DC-AC Inverters

Features

- Low Q_{RR}, Low I_{RRM}, Low t_{RR}
- High dl_F/dt capable (1000A/μs)
- Soft recovery

Benefits

- Increases efficiency
 - Eliminates need for snubber circuits
 - Reduces EMI filter component size & count
- · Enables extremely fast switching

Absolute Maximum Ratings

Absolute maximum ratings are the values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Symbol	Parameter	Conditions	Rating	Units
V _{RRM}	Peak repetitive reverse voltage		600	V
I _{F(AVG)}	Average forward current	T _J = 150 °C, T _C = 100 °C	20	Α
I _{FSM}	Non-repetitive peak surge current	60 Hz, ½ cycle	105	Α
I _{FSM}	Non-repetitive peak surge current	$1/2$ cycle of t=28 μ s Sinusoid, T _C =25 °C	350	Α
$T_{J(MAX)}$	Maximum junction temperature		150	°C
T _{STG}	Storage temperature		-55 to 150	°C
	Lead soldering temperature	Leads at 1.6 mm from case, 10 sec	300	°C
P _D	Power dissipation	T _C = 25 °C	125	W
V_{RRM}	Peak repetitive reverse voltage		600	V

Thermal Resistance

Symbol	Resistance from:	Conditions	Rating	Units
$R_{\theta JA}$	Junction to ambient	TO-220	62	°C/W
$R_{\theta JC}$	Junction to case	TO-220	1.0	°C/W

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Electrical Specifications at T_J= 25 °C (unless otherwise specified)

Symbol	Parameter	Conditions		Min	Тур	Max	Units
DC Chara	DC Characteristics						
I _R	Reverse current	$V_R = 600V, T_J = 25$	C	-	-	250	μΑ
		$V_R = 600V, T_J = 125$	°C	-	2.0	-	mA
V _F	Forward voltage	I _F = 20A, T _J = 25 °C		-	2.5	3.1	V
		I _F = 20A, T _J = 150 °C	0	-	2.3	-	V
CJ	Junction capacitance	V _R = 10V, 1 MHz		-	92	-	pF
Dynamic	Characteristics						
t _{RR}	Reverse recovery time	dI/dt =200 A/μs	T _J =25 °C	-	26.5	-	ns
		V _R =400 V, I _F =20 A	T _J =125 °C	-	41.3	-	ns
Q _{RR}	Reverse recovery charge	dI/dt =200 A/μs	T _J =25 °C	-	51	80	nC
		$V_R=400 \text{ V}, I_F=20 \text{ A}$	T _J =125 °C	-	140	-	nC
I _{RRM}	Maximum reverse	dI/dt =200 A/μs	T _J =25 °C	-	3.0	4.0	Α
	recovery current	V _R =400 V, I _F =20 A	T _J =125 °C	-	5.0	-	Α
S t _b			T _J =25 °C	-	0.7	-	
	Softness factor = $\frac{t_b}{t_a}$	V _R =400 V, I _F =20 A	T _J =125 °C	-	0.4	-	

Note to component engineers: X-Series diodes employ Schottky technologies in their design and construction. Therefore, Component Engineers should plan their test setups to be similar to those for traditional Schottky test setups. (For additional details, see Application Note AN-300.)

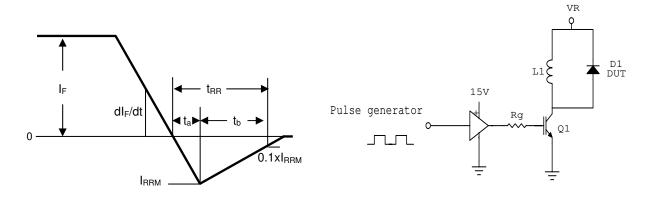
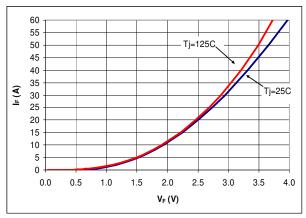


Figure 1. Reverse Recovery Definitions

Figure 2. Reverse Recovery Test Circuit

Electrical Specifications at T_J= 25 °C (unless otherwise specified)



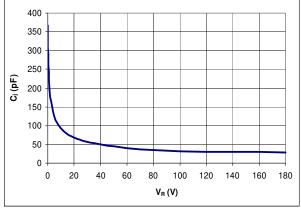
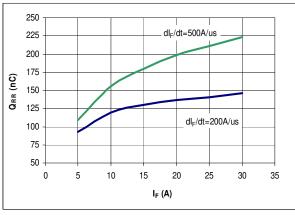


Figure 3. Typical I_F vs V_F

Figure 4. Typical C, vs V,



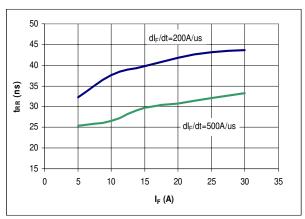
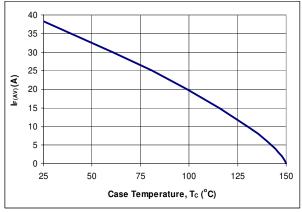


Figure 5. Typical Q_{RR} vs I_F at $T_J = 125$ °C

Figure 6. Typical t_{RR} vs I_F at T_J = 125 °C



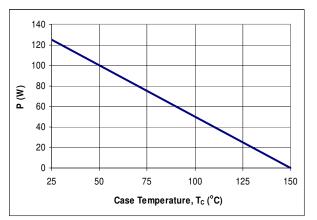


Figure 7. DC Current Derating Curve

Figure 8. Power Derating Curve

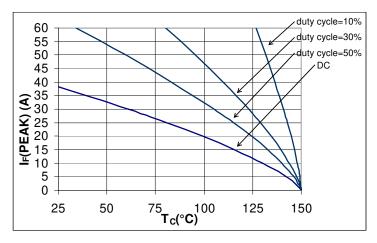


Figure 9. $I_F(PEAK)$ vs T_c , f=70 kHz

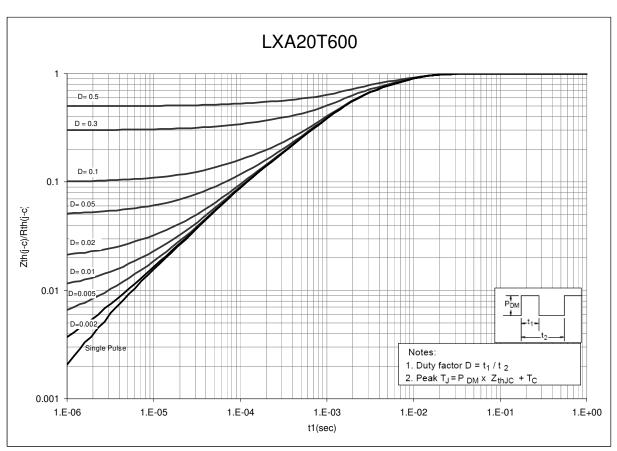
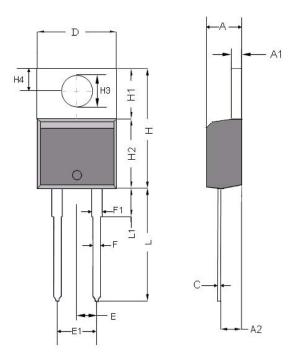


Figure 10. Normalized Maximum Transient Thermal Impedance

Dimensional Outline Drawings



	Millimeters		
Dim	MIN MAX		
Α	4.32	4.70	
A 1	1.14	1.40	
A 2	2.03	2.79	
С	0.34	0.610	
D	9.65	10.67	
E	2.49	2.59	
E1	4.98	5.18	
F	0.508	1.016	
F1	1.14	1.78	
Н	14.71	16.51	
H1	5.84	6.55	
H2	8.51	9.25	
Н3	3.53	3.96	
H4	2.54	3.05	
L	12.70	14.22	
L1	-	6.35	

Mechanical Mounting Method	Maximum Torque / Pressure specification	
Screw through hole in package tab	1 Newton Meter (nm) or 8.8 inch-pounds (lb-in)	
Clamp against package body	12.3 kilogram-force per square centimeter (kgf/cm ²) or 175 lbf/in ²	

Soldering time and temperature: This product has been designed for use with high-temperature, lead-free solder. The component leads can be subjected to a maximum temperature of 300 °C, for up to 10 seconds. See Application Note AN-303, for more details.

Ordering Information

Part Number	Package	Packing
LXA20T600	TO-220AC	50 units/tube

The information contained in this document is subject to change without notice.



LXA20T600

Revision	Notes	Date
1.0	Released by Qspeed	09/09
1.1	Converted to Power Integrations Document	01/11



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Power Integrations Worldwide Sales Support Locations

WORLD HEADQUARTERS

5245 Hellyer Avenue San Jose, CA 95138, USA. Main: +1-408-414-9200 Customer Service: Phone: +1-408-414-9665 Fax: +1-408-414-9765

e-mail:

usasales@powerint.com

CHINA (SHANGHAI)

Rm 1601/1610, Tower 1 Kerry Everbright City No. 218 Tianmu Road West Shanghai, P.R.C. 200070 Phone: +86-021-6354-6323 Fax: +86-021-6354-6325 e-mail: chinasales@powerint.com

CHINA (SHENZHEN)

Rm A, B & C 4th Floor, Block C, Electronics Science and Technology Building 2070 Shennan Zhong Road Shenzhen, Guangdong, P.R.C. 518031 Phone: +86-755-8379-3243

Fax: +86-755-8379-5828

e-mail:

chinasales@powerint.com

GERMANY

Rueckertstrasse 3 D-80336, Munich Germany Phone: +49-89-5527-3911 Fax: +49-89-5527-3920

e-mail:

eurosales@powerint.com

INDIA

#1, 14th Main Road Vasanthanagar Bangalore-560052 India Phone: +91-80-4113-8020 Fax: +91-80-4113-8023 e-mail: indiasales@powerint.com

ITALY

Via De Amicis 2 20091 Bresso MI Italy Phone: +39-028-928-6000 Fax: +39-028-928-6009 e-mail: eurosales@powerint.com

JAPAN

Kosei Dai-3 Building 2-12-11, Shin-Yokohama, Kohoku-ku, Yokohama-shi, Kanagawa 222-0033 Japan

Phone: +81-45-471-1021

Fax: +81-45-471-3717 e-mail: japansales@powerint.com

KOREA

RM 602, 6FL Korea City Air Terminal B/D, 159-6 Samsung-Dong, Kangnam-Gu, Seoul, 135-728 Korea Phone: +82-2-2016-6610 Fax: +82-2-2016-6630

e-mail: koreasales@powerint.com

SINGAPORE

51 Newton Road, #19-01/05 Goldhill Plaza Singapore, 308900 Phone: +65-6358-2160 Fax: +65-6358-2015

singaporesales@powerint.com

TAIWAN

5F, No. 318, Nei Hu Rd., Sec. 1 Nei Hu District Taipei 114, Taiwan R.O.C. Phone: +886-2-2659-4570 Fax: +886-2-2659-4550 *e-mail*:

taiwansales@powerint.com

EUROPE HQ

1st Floor, St. James's House East Street, Farnham Surrey GU9 7TJ United Kingdom Phone: +44 (0) 1252-730-141 Fax: +44 (0) 1252-727-689 e-mail: eurosales@powerint.com

APPLICATIONS HOTLINE World Wide +1-408-414-9660

APPLICATIONS FAX
World Wide +1-408-414-9760

